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B/O FORM PTO 1595 (1/31/92)

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U.S. Department of Commerce
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4459-044

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Sheng Tsung Liu

☐ Additional names of conveying parties attached

2. Name and Address of Receiving Party(ies):

Name: Advanced Semiconductor Engineering, Inc.

Internal Address:

Street Address: No. 26, Chin 3rd Road, Nantze Export Processing Zone

City, State, Zip: Kaoshiung, Taiwan, R.O.C.

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:

Execution Date: March 2, 2001

☐ Additional name(s) and address(es) attached.

4. (a) Patent Application Number(s):

09/811,394

If this document is being filed together with a new application, the execution date of the application is:

4. (b) Patent Numbers:

☐ Additional Numbers Attached.

5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed:

Name: Benjamin J. Hauptman

Address: Lowe Hauptman Gilman & Berner
1700 Diagonal Road, Suite 310
Alexandria, Virginia 22314

6. Total Number of Applications and Patents Involved: 1

7. Total Fee: \$40.00

(37 C.F.R.
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July 23, 2001

Benjamin J. Hauptman, Registration Number 29,310

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Benjamin J. Hauptman, Registration Number 29,310

March 20, 2001

BJH/rhf

Total number of pages comprising cover sheet: 1

J1046 U.S. PTO
09/811394

03/20/01

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Sheng Tsung LIU (4) _____
 (2) _____ (5) _____
 (3) _____ (6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

ELECTRONIC PACKAGE WITH SURFACE-MOUNTABLE DEVICE BUILT THEREIN

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____, or

(b) for which an application for United States Letters Patent was executed on March 2, 2001,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS

DATE SIGNED

1) Sheng Tsung Liu

Name: Sheng Tsung LIU

March 2, 2001

2) _____

Name:

3) _____

Name:

4) _____

Name:

5) _____

Name:

6) _____

Name